

SPECIFICATION

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OLED SPECIFICATION

Model No:

REX012832EYAP3N00000

New Product only for reference

CUSTOMER:

APPROVED BY			
PCB VERSION			
DATE			
FOR CUSTOMER USE	ONLY		
SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
Release DATE:		100	



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2016/02/25		First release
A	2016/06/01		Modify Static
			electricity test
В	2017/01/06		Modify Electrical
			Characteristics



Contents

- 1.General Specification
- 2.Module Classification Information
- 3.Interface Pin Function
- 4.Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
- 6.Electrical Characteristics
- 7.Optical Characteristics
- 8.OLED Lifetime
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

- Module dimension: 33.4× 14.5 × 1.65 mm
- Active area: 25.58×6.38 mm
- Dot Matrix: 128*64
- Pixel size: 0.176 × 0.176 mm
- Pixel pitch: 0.200× 0.200 mm
- Display Mode : Passive Matrix
- Duty: 1/32 Duty
- Display Color: Yellow
- IC: SSD1306BZ



2.Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	E	Х	012832	Е	Y	А	Р	3	Ν	0	0	0	00

1	Brand : Raystar Opt	tronics Inc.
2	E : OLED	
3 4	Dot Matrix : 128*32	Character. G \rightarrow Graphic T \rightarrow TAB .X \rightarrow COG . H \rightarrow COG (with Frame 2
5	Series	
		A : Amber R : Red C : Full Color
6	Emitting Color	B : Blue W : White
0		G : Green Y : Yellow
		S : Sky Blue X : Dual Color
7	Polarizer	P : With Polarizer; N: Without Polarizer
1	Polanzei	A : Anti-glare Polarizer
8	Display Mode	P : Passive Matrix ; N : Active Matrix
9	Driver Voltage	3:3.0~3.3V; 5:5.0V
10	Touch Panel	N : Without touch panel; T: With touch panel
		0 : Standard
		1 : Sunlight Readable
11	Product type	2 : Transparent OLED (TOLED)
		3 : Flexible OLED (FOLED)
		4 : OLED Lighting
		0 : Standard
12	Inspection Grade	2 : B grade
12	inspection Glade	C : Automotive grade
		Y : Consumer grade
13	Interface	0 : Default ; F : FPC ; H : Hot bar ; D : Demo Kit
14	Serial No.	Serial number(00~ZZ)



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3. Interface Pin Function

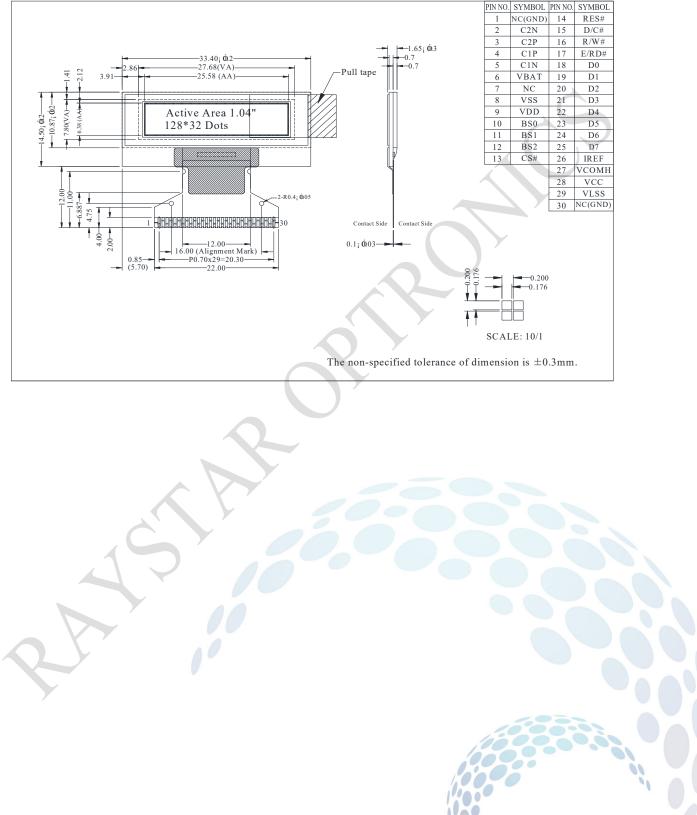
No.	Symbol	Function				
	N.C.	Reserved Pin (Supp	orting Pi	in)		
1	(GND)					es from stresses on the
		function pins. These	pins mu	ist be co	onnecteo	d to external ground.
2	C2N					pacito r Negative Terminal of
3	C2P				• •	p capacitors are required
4	C1P		ls. They	must be	e floateo	d when the converter is not
5	C1N	used.				
0		Power Supply for DO				buffer of the DC/DC voltage
6	VBAT	converter. It must be	connec	ted to ex	xternal s	source when the converter is
	NO		onnected		when t	the converter is not used.
7	NC	NC				
8	VSS	Ground of Logic Circ		ac o rofo	ronco fr	or the logic pins. It must be
0	V33	connected to externa			itence id	or the logic pins. It must be
		Power Supply for Lo		J.		
9	VDD		-	lt must k	ne conn	ected to external source.
		Communicating Prot				
10	BS0	These pins are MCL			tion inni	It. See the
		following table:	menue			
			BS0	BS1	BS2	T
11	BS1	I2C	0	1	0	1
		3-wire SPI	1	0	0	
10		4-wire SPI	0	0	0	
12	BS2	8-bit 68XX Parallel 8-bit 80XX Parallel	0.	0	1	
		Chip Select	v	-	-	
13	CS#	This pin is the chip s	elect inr	out The	chin is	enabled for MCU
15	00#	communication only	· · ·			
		Power Reset for Cor				
14	RES#			-		s low, initialization of the chip
		is executed.	ai input.			
		Data/Command Con	trol			
		This pin is Data/Com	nmand c	ontrol pi	n. Whe	n the pin is pulled high, the
		input at D7~D0 is tre		•		
		When the pin is pulle	ed low, t	he input	at D7~	D0 will be transferred to the
15	D/C#	command register. F	or detai	l relatior	nship to	MCU interface signals,
15	D/0#	please refer to the T				
						ace mode is selected, the
						ulled low, the data at SDIN
					egister.	In I2C mode, this pin acts as
		SA0 for slave addres	ss select	tion.		
		Р	age 8 , To	otal 32 Pa	ges	



17RDBThis is a MPU interface input pad. When connected to an 8080 series MPU, it is active LOW. This pad is connected to the RD signal of the 8080 series MPU, and the data bus is in an output status when this signal is "L". When connected to a 6800 series MPU , this is active HIGH. This is used as an enable clock input of the 6800 series MPU. When RD = "H": Enable. When RD = "H": Enable.18D0This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit19D1standard MPU data bus.20D2When the serial interface is selected, then D0 serves as the serial clock input pad (SCL) and D122D4serves as the serial data input pad (SI). At this time, D2 to D7 are set to high impedance.24D6When the I2C interface is selected, then D0 serves as the serial clock input pad (SCL) and D125D7serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance.26IREFEvenen this pad and VSS. Set the current at 12.5mA.27VCOMHThis is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS.28VPPOLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally.29VLSSThis is a segment voltage reference pad. This pad should be connected to VSS externally.	 ,		
an enable clock input of the 6800 series MPU. When RD = "H": Enable. When RD = "L": Disable. 18 D0 19 D1 standard MPU data bus. 20 D2 When the serial interface is selected, then D0 serves as the serial clock input 21 D3 22 D4 serves as the serial data input pad (SI). At this time, D2 to D7 are set to high 23 D5 impedance. 24 D6 When the I2C interface is selected, then D0 serves as the serial clock input pad (SCL) and D1 25 D7 serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. 26 IREF This is a segment current reference pad. A resistor should be connected between this pad and VSS. Set the current at 12.5mA. 27 VCOMH This is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 29 VL SS	17	RDB	When connected to an 8080 series MPU, it is active LOW. This pad is connected to the RD signal of the 8080 series MPU, and the data bus is in an output status when this
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21 D3 pad (SCL) and D1 22 D4 serves as the serial data input pad (SI). At this time, D2 to D7 are set to high impedance. 23 D5 impedance. 24 D6 When the I2C interface is selected, then D0 serves as the serial clock input pad (SCL) and D1 25 D7 serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. 26 IREF This is a segment current reference pad. A resistor should be connected between this pad and VSS. Set the current at 12.5mA. 27 VCOMH This is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 29 VLSS This is a segment voltage reference pad.	19	D1	
22 D4 serves as the serial data input pad (SI). At this time, D2 to D7 are set to high impedance. 23 D5 impedance. 24 D6 When the I2C interface is selected, then D0 serves as the serial clock input pad (SCL) and D1 25 D7 serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. 26 IREF This is a segment current reference pad. A resistor should be connected between this pad and VSS. Set the current at 12.5mA. 27 VCOMH This is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 29 VLSS This is a segment voltage reference pad.	20	D2	
 D5 impedance. D6 When the I2C interface is selected, then D0 serves as the serial clock input pad (SCL) and D1 serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. D7 Serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. 26 IREF between this pad and VSS. Set the current at 12.5mA. 27 VCOMH This is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 29 VLSS This is a segment voltage reference pad. 	21	D3	
24 D6 When the I2C interface is selected, then D0 serves as the serial clock input pad (SCL) and D1 25 D7 serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. 26 IREF This is a segment current reference pad. A resistor should be connected between this pad and VSS. Set the current at 12.5mA. 27 VCOMH This is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 20 VLSS This is a segment voltage reference pad.	22	D4	
24 D0 pad (SCL) and D1 25 D7 serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. 26 IREF This is a segment current reference pad. A resistor should be connected between this pad and VSS. Set the current at 12.5mA. 27 VCOMH This is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 29 VLSS This is a segment voltage reference pad.	23	D5	
25 D7 serves as the serial data input pad (SDAI). At this time, D2 to D7 are set to high impedance. 26 IREF This is a segment current reference pad. A resistor should be connected between this pad and VSS. Set the current at 12.5mA. 27 VCOMH This is a pad for the voltage output high level for common signals. A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 29 VLSS This is a segment voltage reference pad.	24	D6	
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27 VCOWH A capacitor should be connected between this pad and VSS. 28 VPP OLED panel power supply. Generated by internal charge pump. Connect to capacitor. It could be supplied externally. 29 VLSS This is a segment voltage reference pad.	26	IREF	between this pad and VSS. Set the current at 12.5mA.
20 VPP Connect to capacitor. It could be supplied externally. 20 VLSS This is a segment voltage reference pad.	27	VCOMH	A capacitor should be connected between this pad and VSS.
	28	VPP	
	29	VLSS	
30 NC(GND) No connection	30	NC(GND)	No connection



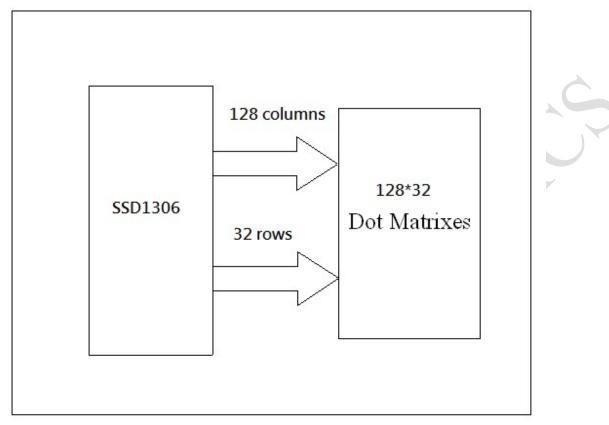
4. Contour Drawing & Block Diagram



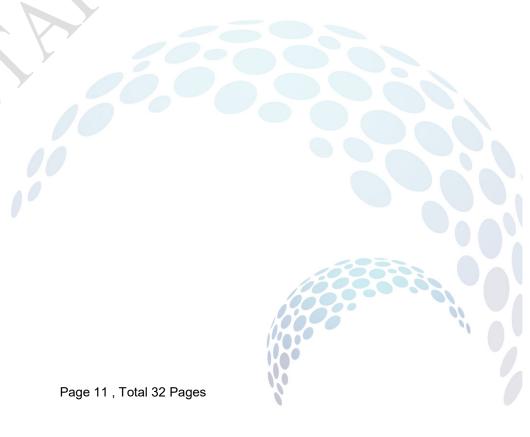
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FUNCTION BLOCK DIAGRAM



*For more information, please refer to Application Note provided by Raystar Optronics.



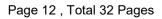


5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	0	4	V	1,2
Supply Voltage for Display	VCC	0	16	V	1,2
Operating Temperature	TOP	-40	+80	°C	—
Storage Temperature	TSTG	-40	+80	°C	_
			(⁽¹⁾) (0)		

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6."Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.





6.Electrical Characteristics

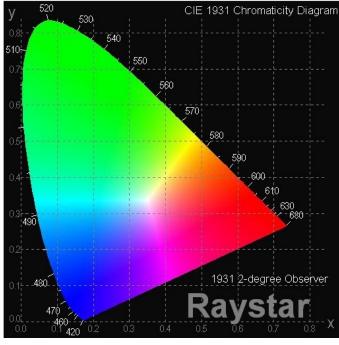
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	7	7.25	7.5	×
Input High Volt.	VIH	_	0.8×VDD	_	VDDIO	V
Input Low Volt.	VIL	_	0		0.2×VDD	V
Output High Volt.	VOH	_	0.9×VDD		VDDIO	V
Output Low Volt.	VOL	-	0		0.1×VDD	V
50% Check Board operat	Vcc =7.25V	4	5	6	mA	

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7.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Мах	Unit
View Angle	(V)θ	-	160	-	-	deg
	(Н)ф	-	160	-		deg
Contrast Ratio	CR	Dark	2000:1			-
Response Time	T rise	-	-	10	-	μs
	T fall	-		10	-	μs
Display with 50% check	s	100	120	-	cd/m2	
CIEx(Yellow)	x,y(CIE1931)	0.45	0.47	0.49	-	
CIEy(Yellow)		x,y(CIE1931)	0.48	0.50	0.52	-





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8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



9.Reliability

Content of Reliability Test

Environmenta	l Test	1	1
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80 □ 240hrs	- (
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40 □ 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80□ 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40□ 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60□,90%RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40 25 80 30min 5min 30min 1 cycle	-40□/80□ 100 cycles	
Mechanical Tes	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	50
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	

*** Supply voltage for OLED system =Operating voltage at 25°C



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item	Criterion						AQL		
01	Electrical Testing	1.1 Missing verti defect. 1.2 Missing char				gme	ent contrast			
		1.3 Display malf	.3 Display malfunction.							
			.4 No function or no display. .5 Current consumption exceeds product specifications.							
		1.6 OLED viewir	.6 OLED viewing angle defect.							
		1.7 Mixed produ 1.8 Contrast def	.7 Mixed product types.							
							Y			
02	Black or white	2.1 White and bl three white or bl	•			nm	, no more than			
	spots on	2.2 Densely spa	•	-		s o	r lines within	2.5		
	OLED (display	3mm.						2.0		
	only)									
03	OLED black	3.1 Round type following drawing			SIZE		Acceptable Q			
	spots, white spots, contamina tion (non-displ	$\Phi = (x + y) / 2$	9		SIZE		TY			
					Ф≦0.10		Accept no dense			
					0.10 < Φ≦0.2	20	2	2.5		
					0.20 < Φ≦0.25		1			
	ay)		0.25 < Φ			0				
		3.2 Line type : (A	As followin	g dr						
			Length		dth	A	cceptable Q TY			
	A			W	≦0.02	A	ccept no dense			
			L≦3.0	0.0)2 < W≦0.03	- 2		2.5		
		Y	L≦2.5	0.0)3 < W≦0.05					
				0.0)5 < W	A	s round type			
04	Polarizer bubbles	If bubbles are vi	sible	Si	ze Φ	Δ	cceptable Q TY			
		judge using blac	k spot		≦0.20		ccept no dense			
		specifications, not to find, must che			20 < Φ≦0.50			2.5		
		specify direction	, ⊢		0.20 < Φ≦0.30 0.50 < Φ≦1.00		10000	2.5		
				0.30 < Φ≦1.00 1.00 < Φ		0	10000			
					tal Q TY	3				
			Dogo 19	Tota	22 Dages		10			
			Page 18,	i ota	32 Pages		8			



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination			
			t: Glass thickness a gth:	Chip thickness : OLED side length	
			surface and crack bet	ween panels:	
		z: Chip thickness	y: Chip width	v: Chin longth	
		Z≦1/2t	Not over viewing area	x: Chip length x≦1/8a	
)6	Chipped glass	1/2t < z≦2t	Not exceed 1/3k	x≦1/8a	2.5
 ⊙If there are 2 or more chips, x is total lengt 6.1.2 Corner crack: 		ngth of each chip.			
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	
	h ()	1/2t < z≦2t	Not exceed 1/3k	x≦1/8a	
		⊙If there are 2 or mo	ore chips, x is the tota	l length of each chip.	



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Item	Criterion			AQL	
	Symbols :				
	L: Electrode pad length				
	0.2.1 Only on electrode pad .				
	va Chin width	v. Chin longth	T: Chin thickness		
			0 < 2 = 1		
			Y		
Class					
crack				2.5	
	y: Chip width	x: Chip length			
	v≤l	x≤1/8a			
	·				
	specifications.				
	⊙If the product will be heat sealed by the customer, the alignment				
7	mark not be damaged.				
		y≞1/3L	x≧a		
			100	101	
			1000		
	Glass	Symbols : x: Chip length y: k: Seal width t: L: Electrode pad length 6.2 Protrusion over ter 6.2.1 Chip on electrode $y: Chip width$ $y \leq 0.5 mm$ 6.2.2 Non-conductive 6.2.2 Non-conductive fGlass crackglass cracky: Chip width $y \leq L$ 0 If the chipped area to must remain and be specifications. 0 If the product will be mark not be damage	Symbols : x: Chip length k: Seal width t: Glass thickness L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : $y:$ Chip width $y \leq 0.5$ mmx: Chip length x $\leq 1/8a$ 6.2.2 Non-conductive portion:Glass crack $y:$ Chip width $y \leq L$ $y:$ Chip width $y \leq L$ x:< Chip length x $\leq 1/8a$ Olf the chipped area touches the ITO ter must remain and be inspected accordi specifications.Olf the product will be heat sealed by the mark not be damaged.	Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : 9 9.1 Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z ≤ t	



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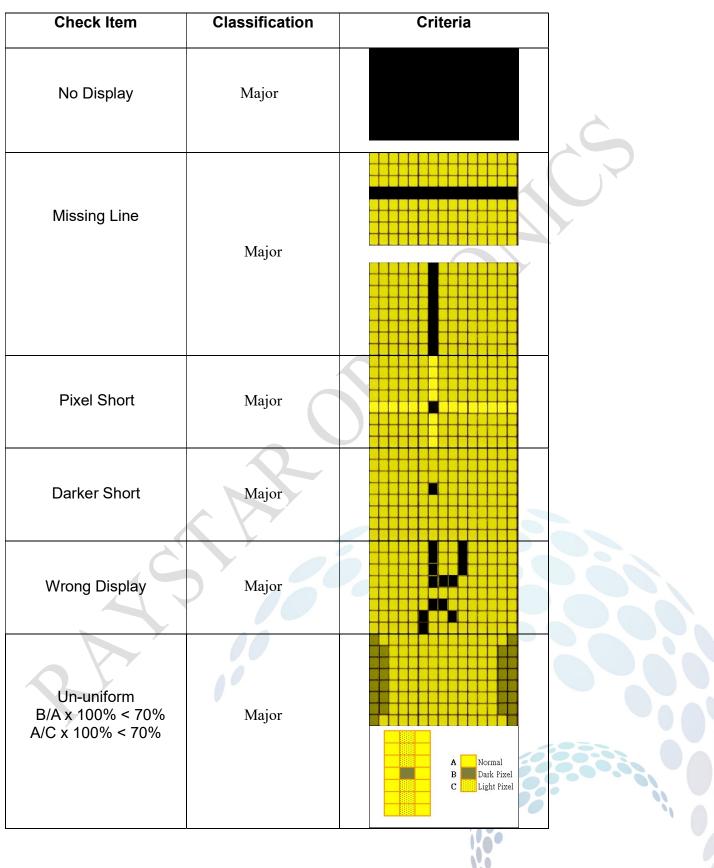


NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	 2.5 2.5 2.5 2.5 0.65 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



Item	Criterion	AQL
General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5 0.65
		2.5
		2.5
		2.5
		0.5
		2.5
		2.5
	chip component) is not burned into brown or black color.	0.65
	12.7 Sealant on top of the ITO circuit has not hardened.	0.65
	12.8 Pin type must match type in specification sheet.	0.65
	12.9 OLED pin loose or missing pins.	
	12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
	12.11 Product dimension and structure must conform to product specification sheet.	
	General	General appearance12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.





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11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)

(11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

11.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

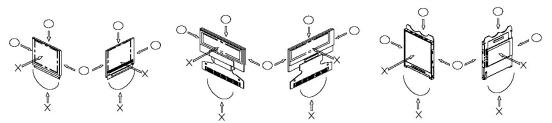
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

* Water

* Ketone

- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.

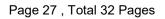




- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.(We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.





11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.



		Page: 1		
<u>Modu</u>	le Sample	e Estimate Feedback Sheet		
Module Number :	Module Number :			
1、Panel Specification :	1			
1. Panel Type:	□ Pass	□NG ,		
2. Numbers of Pixel :	Pass	□NG ,		
3. View Area:	Pass	□NG ,		
4. Active Area :	Pass	□NG ,		
5.Emitting Color :	Pass	□NG ,		
6.Uniformity :	□Pass	□NG ,		
7.Operating	Pass	□NG ,		
Temperature :				
8.Storage Temperature :	Pass	□NG ,		
9.Others :				
2. Mechanical Specificati	on :			
1. PCB Size :	□Pass	□NG ,		
2.Frame Size :	□Pass	□NG ,		
3.Materal of Frame :	□Pass	□NG ,		
4.Connector Position :	□Pass	□NG ,		
5.Fix Hole Position :	□Pass	□NG ,		
6. Thickness of PCB :	□Pass	□NG ,		
7. Height of Frame to	□Pass	□NG ,		
PCB :				
8.Height of Module :	□Pass	□NG ,		
9.Others :	□Pass	□NG ,		
3、Relative Hole Size :	1			
1.Pitch of Connector :	□Pass	□NG ,		
2.Hole size of	□Pass	□NG ,		
Connector :		120000		
3.Mounting Hole size :	□Pass	□NG ,		
4.Mounting Hole Type :	□Pass	□NG ,		



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Module Number : ____

Pa	g	e	:	2

4、Electronic Characteristics of Module :

□Pass	□NG ,
□Pass	□NG ,
□Pass	□NG ,
□Pass	□NG ,
□Pass	□NG ,
□Pass	□NG ,
□Pass	□NG ,
□Pass	□NG ,
	□Pass □Pass □Pass □Pass □Pass □Pass

5、<u>Summary</u>:

Sales signature : _____ Customer Signature : _____

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